

Title (en)

METHOD FOR ELECTROLESS NICKEL PLATING

Title (de)

VERFAHREN ZUR CHEMISCHEN VERNICKELUNG

Title (fr)

PROCEDE DE DEPOT AUTOCATALYTIQUE DE NICKEL

Publication

EP 1343921 B1 20050316 (EN)

Application

EP 01992803 A 20011004

Priority

- DE 10054544 A 20001101
- EP 0111468 W 20011004

Abstract (en)

[origin: WO0236853A1] A method for electroless metal plating of substrates, more specifically with electrically non-conductive surfaces, by which the substrates may be reliably metal plated at low cost under manufacturing conditions as well and by means of which it is possible to selectively coat the substrates to be treated only, and not the surfaces of the racks. The method involves the following steps: a. pickling the surfaces with a solution containing chromate ions; b. activating the pickled surfaces with a silver colloid containing stannous ions; c. treating the activated surfaces with an accelerating solution in order to remove tin compounds from the surfaces; and d. depositing, by means of an electroless nickel plating bath, a layer that substantially consists of nickel to the surfaces treated with the accelerating solution, the electroless nickel plating bath containing at least one reducing agent selected from the group comprising borane compounds.

IPC 1-7

C23C 18/16; **C23C 18/20**; **C23C 18/24**; **C23C 18/28**; **C23C 18/32**; **C23C 18/34**; **C23C 18/44**; **C23C 18/50**; **C23C 18/18**

IPC 8 full level

C23C 18/16 (2006.01); **C23C 18/18** (2006.01); **C23C 18/20** (2006.01); **C23C 18/24** (2006.01); **C23C 18/28** (2006.01); **C23C 18/30** (2006.01); **C23C 18/32** (2006.01); **C23C 18/34** (2006.01); **C23C 18/44** (2006.01); **C23C 18/50** (2006.01)

CPC (source: EP US)

C23C 18/1844 (2013.01 - EP US); **C23C 18/1893** (2013.01 - EP US); **C23C 18/2086** (2013.01 - EP US); **C23C 18/28** (2013.01 - EP US); **C23C 18/34** (2013.01 - EP US); **C23C 18/50** (2013.01 - EP US)

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

WO 0236853 A1 20020510; AT E291106 T1 20050415; AU 1695302 A 20020515; CA 2425575 A1 20020510; CN 1314835 C 20070509; CN 1473207 A 20040204; DE 10054544 A1 20020508; DE 60109486 D1 20050421; DE 60109486 T2 20060406; EP 1343921 A1 20030917; EP 1343921 B1 20050316; ES 2237615 T3 20050801; JP 2004513229 A 20040430; JP 3929399 B2 20070613; TW I253481 B 20060421; US 2004086646 A1 20040506; US 6902765 B2 20050607

DOCDB simple family (application)

EP 0111468 W 20011004; AT 01992803 T 20011004; AU 1695302 A 20011004; CA 2425575 A 20011004; CN 01818348 A 20011004; DE 10054544 A 20001101; DE 60109486 T 20011004; EP 01992803 A 20011004; ES 01992803 T 20011004; JP 2002539589 A 20011004; TW 90125100 A 20011011; US 41558503 A 20030609